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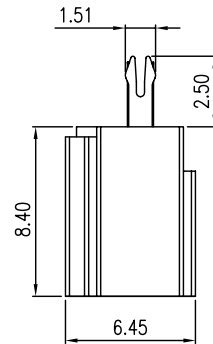
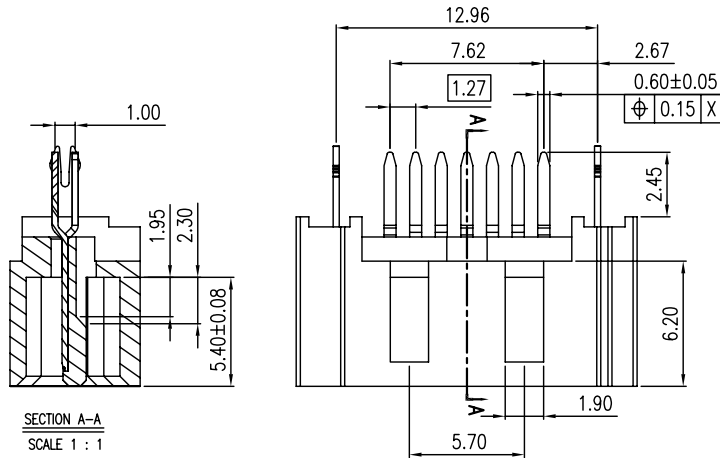
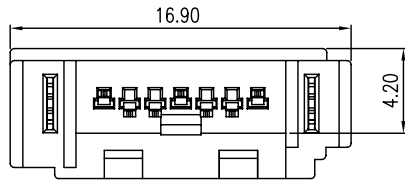
The marking on this product doesn't contain environmental hazardous materials per Material Specification 55-00259 for Sony GP compliant or per directive 2002/95/EC for RoHS compliant.



ORIGINAL



REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		UNAPPROVED REVISION	06/04/2009	Roger Tsai



NOTES:

1. MATERIAL:

HOUSING: HIGH TEMPERATURE THERMO PLASTIC UL94V-0  
 TERMINAL: COPPER ALLOY T= 0.30 ±0.01 mm.  
 BOARBLOCK: COPPER ALLOY T= 0.30 ±0.01mm.

2. FINISH:

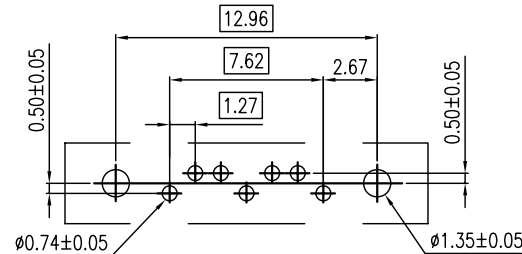
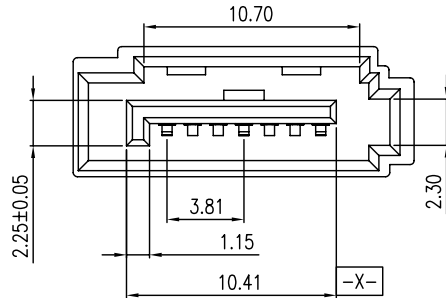
TERMINAL:

CONTACT AREA: SELECTIVE GOLD PLATED.  
 SOLDERING AREA: MATTE TIN PL. 150 μ" THK MIN.  
 UNDER PL.: NICKEL PL. 50 μ" THK MIN.

BOARBLOCK:

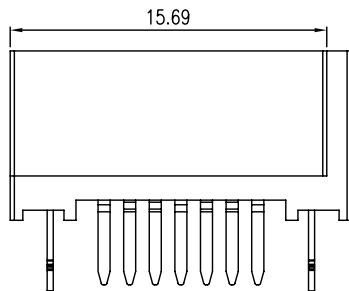
SOLDERING AREA: MATTE TIN PL. 100 μ" THK MIN.  
 UNDER PL.: NICKEL PL. 50 μ" THK MIN.

3. THIS PRODUCT DOESN'T CONTAIN ENVIRONMENTAL HAZARDOUS PER DIRECTIVE 2002/95/EC FOR RoHS COMPLIANT.  
 4. PACKING IS PER AMTA PACKING SPECIFICATION PKS-G16AD001.



RECOMMEND PCB LAYOUT

G16AD X 21QMEU  
 CONTACT FINISH 0: GOLD FLASH  
 1: 15u" GOLD  
 2: 30u" GOLD



TOLERANCE	DRAWN	APPROVALS	DATE	TITLE	UNIT	SIZE	PART No.
X. ±0.30	DESIGNED	Daniel Hsieh	06/04/2009	SATA CONNECTOR 7 POS., 1.27 PITCH, VERTICAL, DIP TYPE	mm	A3	G16ADX210MEU
X.X ±0.20	CHECKED	Roger Tsai	06/04/2009				
X.XX ±0.10	APPROVED	Arron Lin	06/04/2009		NA	1 OF 1	G16ADX210MEU
X.XXX ±0.10	DWG TYPE	CUST DWG	PROJECT CODE				
ANGULAR ±1°							
UNLESS OTHERWISE SPECIFIED							

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